

Dual N-Channel Enhancement Mode Field Effect Transistor

Features

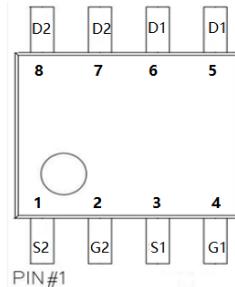
V_{DS} (V) = 20V

I_D = 7A

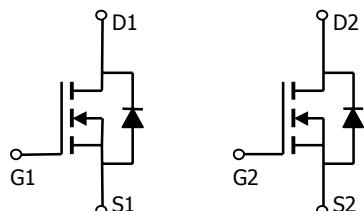
$R_{DS(ON)} < 26m\Omega$ ($V_{GS} = 4.5V$)

$R_{DS(ON)} < 33m\Omega$ ($V_{GS} = 2.5V$)

$R_{DS(ON)} < 42m\Omega$ ($V_{GS} = 1.8V$)



SOP-8



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum		Units
Drain-Source Voltage	V_{DS}	20		V
Gate-Source Voltage	V_{GS}	± 8		V
Continuous Drain Current ^A	I_D	7		A
$T_A=70^\circ C$		6		
Pulsed Drain Current ^B	I_{DM}	40		
Power Dissipation	P_D	2		W
$T_A=70^\circ C$		1.44		
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	R_{0JA}	48	62.5	°C/W
Steady-State		74	110	°C/W
Maximum Junction-to-Lead ^C	R_{0JL}	35	40	°C/W

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Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=16\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.3	0.5	0.8	V
$I_{D(\text{ON})}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	30			A
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=7\text{A}$		21.6	26	$\text{m}\Omega$
			$T_J=125^\circ\text{C}$	29.2	36	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}, I_D=5\text{A}$		26.4	33	$\text{m}\Omega$
		$V_{GS}=1.8\text{V}, I_D=4\text{A}$		33.3	42	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=5\text{A}$		22		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}$		0.76	1	V
I_S	Maximum Body-Diode Continuous Current				3	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$		1050		pF
C_{oss}	Output Capacitance			163		pF
C_{rss}	Reverse Transfer Capacitance			129		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		4		Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=7\text{A}$		15.2		nC
Q_{gs}	Gate Source Charge			1		nC
Q_{gd}	Gate Drain Charge			4		nC
$t_{D(\text{on})}$	Turn-On Delay Time	$V_{GS}=5\text{V}, V_{DS}=10\text{V}, R_L=1.5\Omega, R_{\text{GEN}}=3\Omega$		6.5		ns
t_r	Turn-On Rise Time			9		ns
$t_{D(\text{off})}$	Turn-Off Delay Time			56.5		ns
t_f	Turn-Off Fall Time			13.2		ns
t_{rr}	Body Diode Reverse Recovery time	$I_F=5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		21		ns
Q_{rr}	Body Diode Reverse Recovery charge	$I_F=5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		7.1		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

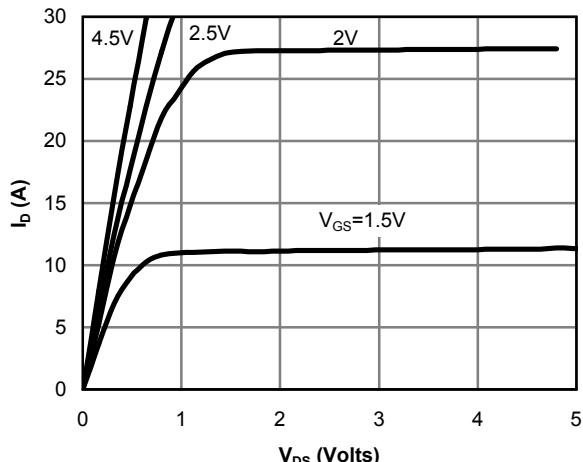


Fig 1: On-Region Characteristics

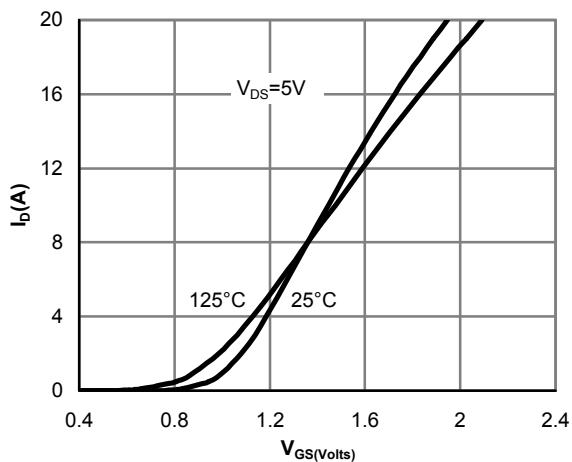


Figure 2: Transfer Characteristics

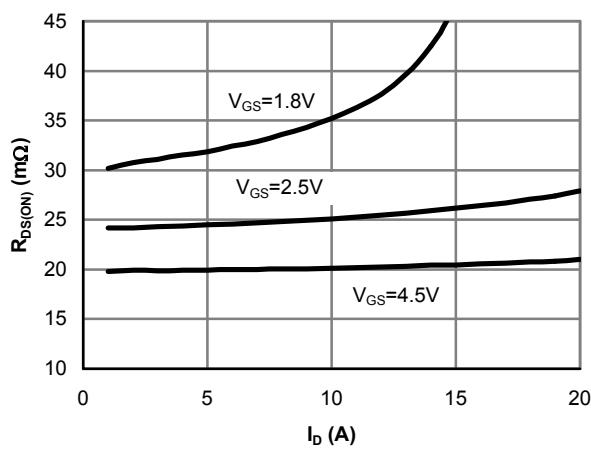


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

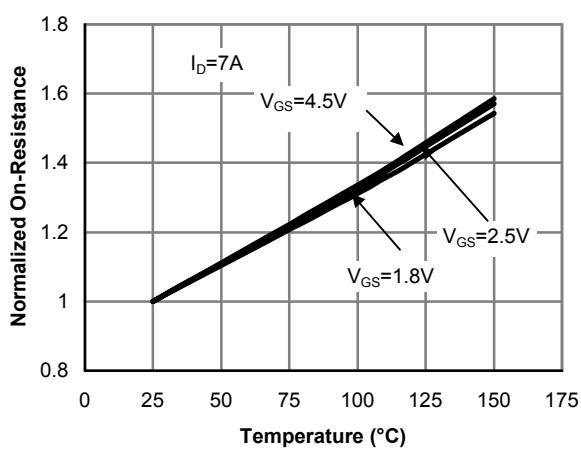


Figure 4: On-Resistance vs. Junction Temperature

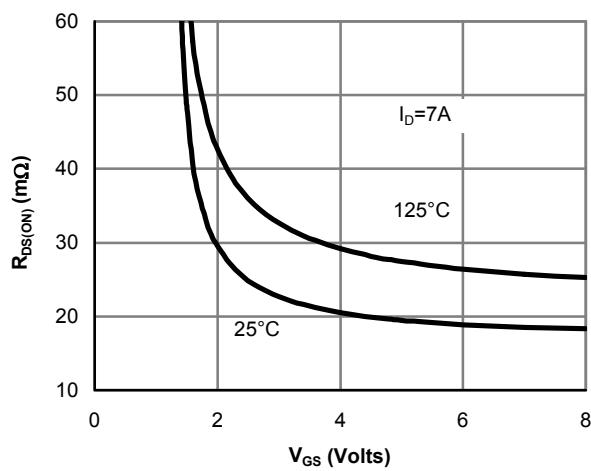


Figure 5: On-Resistance vs. Gate-Source Voltage

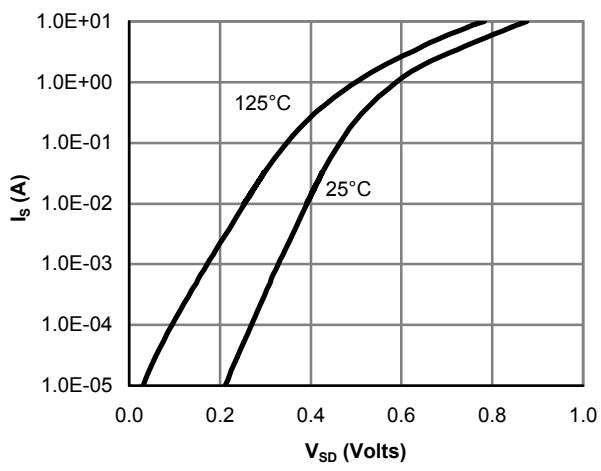


Figure 6: Body-Diode Characteristics

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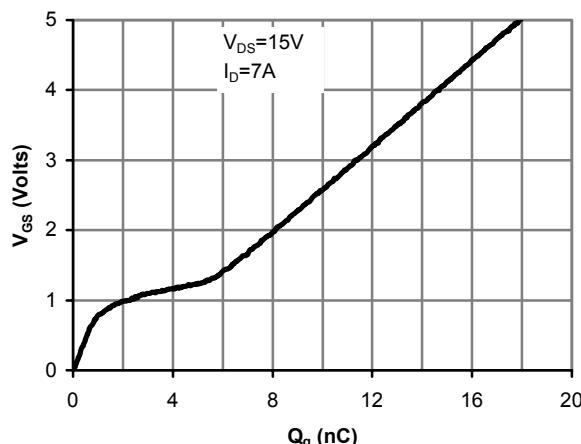


Figure 7: Gate-Charge Characteristics

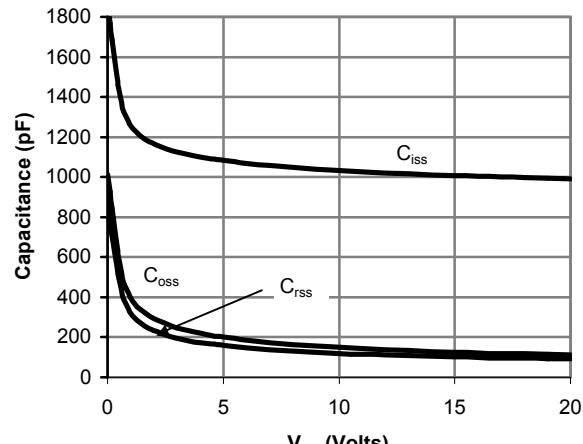


Figure 8: Capacitance Characteristics

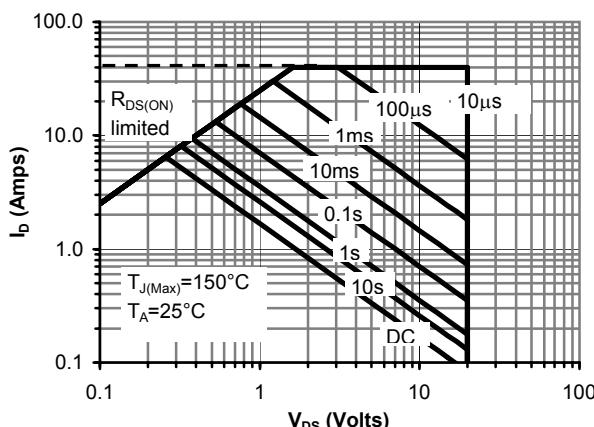


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

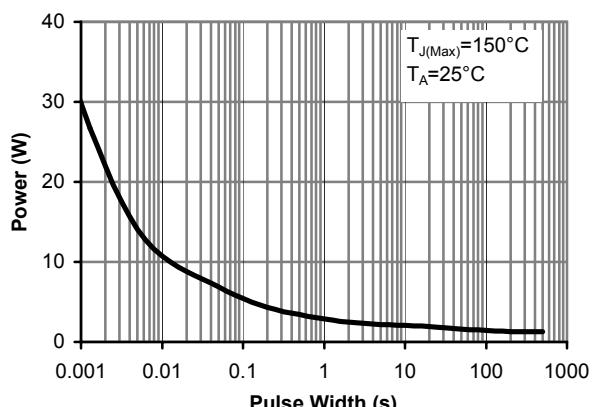


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

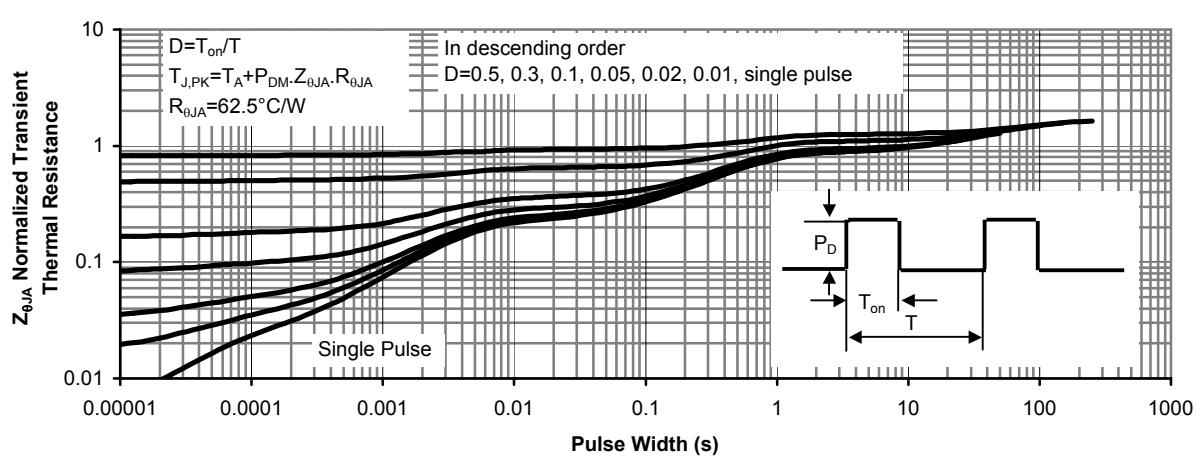
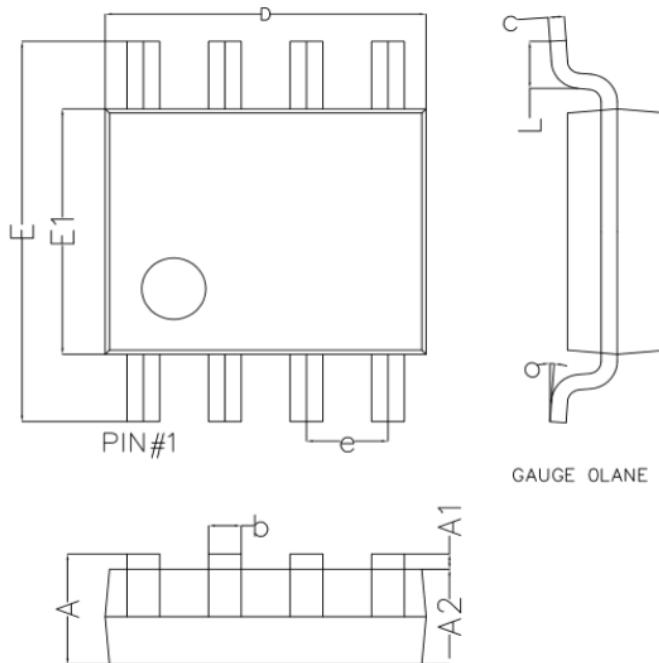


Figure 11: Normalized Maximum Transient Thermal Impedance

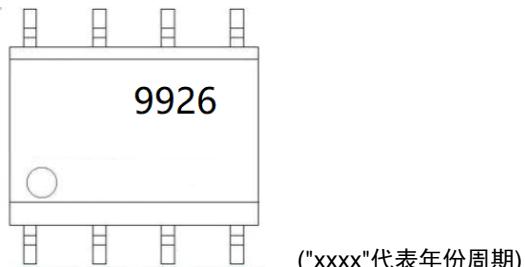
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Package Mechanical Data-SOP-8



Symbol	Dim in mm		
	Min	Nor	Max
A	1.350	1.550	1.750
A1	0.100	0.175	0.250
A2	1.350	1.450	1.550
b	0.330	0.420	0.510
c	0.170	0.210	0.250
D	4.800	4.900	5.000
e	1.270 (BSC)		
E	5.800	6.000	6.200
E1	3.800	3.900	4.000
L	0.400	0.835	1.2700
o	0°	4°	8°

Marking



Ordering information

Order Code	Package	Baseqty	Deliverymode
CEM9926A	SOP-8	3000	Tape and reel